



Title of Change:	Addition of ASE Shanghai, China as qualified assembly site for QFN devices.	
Proposed first ship date:	3 September 2015	
Contact information:	Contact your local ON Semiconductor Sales Office or Norhayati Othman <norhayati.othman@onsemi.com>	
Samples:	Contact your local ON Semiconductor Sales Office	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Chean Ching Sim <Cheanching.sim@onsemi.com>	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <PCN.Support@onsemi.com>.	
Change Part Identification:	Marking of the month date codes: Seremban Malaysia assembled devices: M ASE Shanghai assembled devices: 	
Change category(s):	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Product specific change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Test Change <input type="checkbox"/> Material Change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____	
Sites Affected:	Site 1	Site 2
<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : <input checked="" type="checkbox"/> External Foundry/Subcon site(s):	Advanced Semiconductor Engineering Shanghai	
Description and Purpose:		
<p>This is the final notification announcing that ON Semiconductor is qualifying an additional assembly site for the list of QFN products included in this notification (please refer to the "List of Affected Standard Parts" section for the complete device list). The additional assembly site is the ASE Shanghai factory located in China. This facility is ISO/TS16949:2009 certified and has already been qualified and utilized by ON Semiconductor.</p> <p>Two devices have been identified as qualification vehicles, based on the package dimension, die size and volumes. Full electrical characterization over temperature on all devices was performed to ensure that device functionality and electrical specifications are met.</p> <p>Upon expiration or approval of the FPCN, devices listed in this final PCN will have ASE Shanghai as an additional assembly site. Customers may receive devices assembled at either our in-house Seremban, Malaysia assembly site or ASE Shanghai assembly site after that time.</p> <p>There is a difference in mold compound and lead finish for the ASE Shanghai assembly site that is identified below. The location of the assembly site can be identified by the date code marking (see "Changed Part Identification" section for details).</p>		
Lead Finish Difference:		
1. Seremban: Matte Tin (e3 – on the device label) 2. ASE: NiPdAu (e4 – on the device label)		
Mold compound Difference:		
1. Seremban: Sumitomo G760 2. ASE: G631HQ		



Reliability Data Summary:

Package: **UDFN10**

Qual Vehicle: **ESD8004MUTAG**

Qualification Results and Analysis:

Test	Conditions	Interval	Results
HTRB	TA=150C, 80% Rated Voltage	1008 hrs	0/672
SAT	NA	NA	Pass

Conclusion: All reliability requirements have been met.

Package: **UDFN10**

Qual Vehicle: **ESD8104MUTAG**

Qualification Results and Analysis:

Test	Conditions	Interval	Results
HTRB	TA=150C, 80% Rated Voltage	1008 hrs	0/672
SAT	NA	NA	Pass

Conclusion: All reliability requirements have been met.

Electrical Characteristic Summary:

No changes in electrical specifications; all product performance meets current datasheet specifications.

List of affected Standard Parts:

Device	SBN	ASE
ESD8004MUTAG	E	N
ESD8104MUTAG	E	N
ESD8006MUTAG	E	N
ESD8008MUTAG	E	N
ESD8004TMUTAG	E	N
ESD8040MUTAG	E	N
ESD8106MUTAG	E	N
ESD7504MUTAG	E	N
ESD7408MUTAG	E	N

Note: E – Existing Assembly Site

N – New Assembly Site